INTEL ICE LAKE-D XEON PROCESSORS conga-B7XI





- Industrial Use Condition with extended Temperature options
- 32 PCIe Express lanes
- Al Capabilities with Intel® DL boost
- Real Time Capable Platform
- Supporting up to 128 GB DDR4 2666MT/s
 Memory

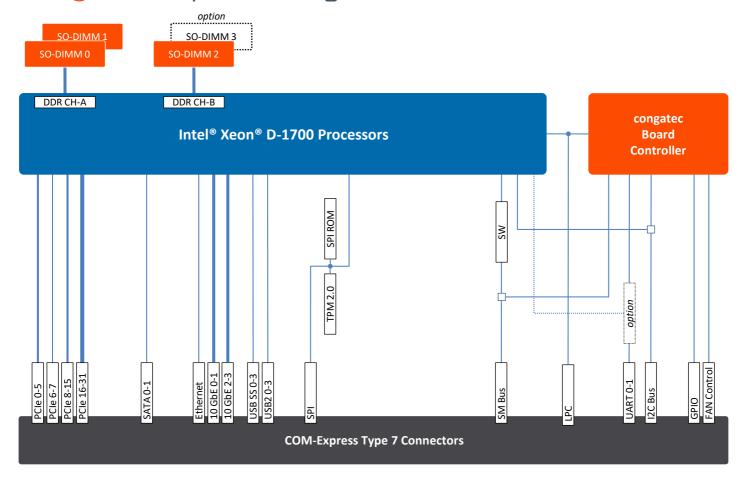
Form Factor	COM Express® Basic, (125 x 95 mm) Type 7 connector pinout						
CPU	Processor	Cores/Threads	Base Frequency	TDP	Cache	Intel Use Condition	
	Xeon® D-1746TER Xeon® D-1732TE Xeon® D-1715TER Xeon® D-1735TR Xeon® D-1712TR	10C/20T 8C/16T 4C/8T 8C/16T 4C/8T	2.0GHz 1.9GHz 2.4GHz 2.2GHz 2.0GHz	67W 52W 50W 59W 39W	15MB 15MB 10MB 15MB 10MB	Industrial (Industrial Temp -40°C to 85°C) Industrial (Industrial Temp -40°C to 85°C) Industrial (Extended Temp -40°C to 80°C) Industrial (Commercial Temp 0°C to 60°C) Industrial (Commercial Temp 0°C to 60°C)	
Chipset	Integrated in SoC						
DRAM	Up to 4x SO-DIMM sockets (on request) for DDR4 memory modules up to 32 GByte each (128 GByte total) with 2666 MT/s (optionally with ECC support)						
Ethernet	1x 2.5GbE TSN Ethernet 4x 10GbE supporting CEI/KR/SFI						
I/O Interfaces	16x PCle Gen4 16x PCle Gen3 4x USB 3.0 4x USB 2.0 2x SATA III (6Gb/s) SPI 2x UART 8x GPIO						
congatec Board controller	Multi Stage Watchdog non-volatile User Data Storage Manufacturing and Board Information Board Statistics I ² C bus (fast mode, 400 kHz, multi-master) Power Loss Control Hardware Health Monitoring POST Code redirection						
Embedded BIOS Feature	AMI Aptio® UEFI firmware 64 Mbyte serial SPI with congatec Embedded BIOS feature OEM Logo OEM CMOS Defaults Flash Update						
Security	Trusted Platform Module (TPM 2.0)						
Power Management	ACPI 5.0 with battery support						
Operating Systems	Microsoft® Windows 10 Microsoft® Windows 10 IoT Enterprise Microsoft® Windows IoT 10 Core Linux Android Yocto RTS Hypervisor						
Temperature Range	Commercial: Or Industrial: Or		ature: 0 to +60°C ature: -40 to +85°C*			rature: -20 to +85°C rature: -40 to +85°C*	
Humidity	-	to 90% r. H. non to 95% r. H. non c					
Size	125 x 95 mm ²						

^{*} Depending on CPU

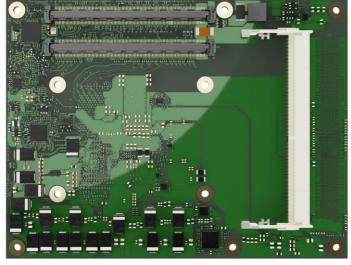




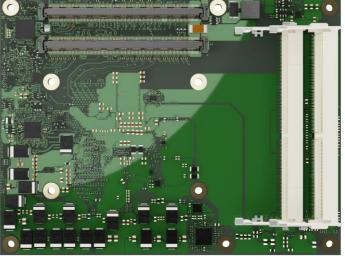
conga-B7XI | Block Diagram



conga-B7XI | Bottom Side View







4x SODIMM sockets (PN 050220)



conga-B7XI | Order Information

Article	PN	Description				
conga-B7XI/D1746TER	050200	COM Express Type 7 Basic module based on Intel® Xeon® D-1746TER 10-core processor w GHz, 15MB cache and dual channel DDR4 2666 MT/s memory interface (formerly Ice Lak LCC). Industrial temperature range from -40°C to 85°C.				
conga-B7XI/D1732TE	050201	COM Express Type 7 Basic module based on Intel® Xeon® D-1732TE 8-core processor with 1.9 GHz, 15MB cache and dual channel DDR4 2666 MT/s memory interface (formerly Ice Lake-D LCC). Industrial temperature range from -40°C to 85°C.				
conga-B7XI/D1715TER	050202	COM Express Type 7 Basic module based on Intel® Xeon® D-1715TER 4-core processor with 2.4 GHz, 10MB cache and dual channel DDR4 2666 MT/s memory interface (formerly Ice Lake-D LCC). Industrial temperature range from -40°C to 80°C.				
conga-B7XI/D1735TR	050210	COM Express Type 7 Basic module based on Intel® Xeon® D-1735TR 8-core processor with 2.2 GHz, 15MB cache and dual channel DDR4 2666 MT/s memory interface (formerly Ice Lake-D LCC). Commercial temperature range from 0°C to 60°C.				
conga-B7XI/D1712TR	050211	COM Express Type 7 Basic module based on Intel® Xeon® D-1712TR 4-core processor with 2.0 GHz, 10MB cache and dual channel DDR4 2400 MT/s memory interface (formerly Ice Lake-D LCC). Commercial temperature range from 0°C to 60°C.				
conga-B7XI/D1746TER-4S	050220	COM Express Type 7 Basic module based on Intel® Xeon® D-1746TER 10-core processor with 2.0 GHz, 15MB cache and dual channel DDR4 2666 MT/s memory interface (formerly Ice Lake-D LCC). Industrial temperature range from -40°C to 85°C 4x SODIMM sockets.				
conga-B7XI/CSA-HP	050250	Standard active cooling solution for COM Express Basic modules conga-B7XI with integrated heat pipes, 39.5mm overall cooling height and integrated 12V fan.				
conga-B7XI/CSP-HP	050252	Standard passive cooling solution for COM Express Basic modules conga-B7XI with integrate heat pipes, 23.3mm overall cooling height.				
conga-B7XI/HSP-HP-B	050254	Standard heatspreader for COM Express Basic modules conga-B7XI with integrated heat pip and 11mm overall cooling height. Through hole mounting with bore hole standoffs Ø2.7mm.				
conga-B7XI/HSP-HP-T	050255	Standard heatspreader for COM Express Basic modules conga-B7XI with integrated heat pip and 11mm overall cooling height. Threaded mounting with threaded standoffs M2.5.				
conga-B7XI/HPA	050256	Heat pipe Adapter for COM Express Basic modules conga-B7XI. Suitable for standard 8 mm heat pipes to optimize heat distribution.				
conga-X7EVAL	065420	Evaluation Carrier Board for COM Express Type 7 modules with up to four 10GbE SFP+ fiber/copper ports implemented via Intel Cortina 10GbE Phy's. The carrier features an As AST2500 Board Management Controller (BMC).				

